

GSE033HB1D3F

ESD Protection Diode

Product Description

It is designed to protect sensitive electronics from damage due to electrostatic discharge (ESD) and other transient events.

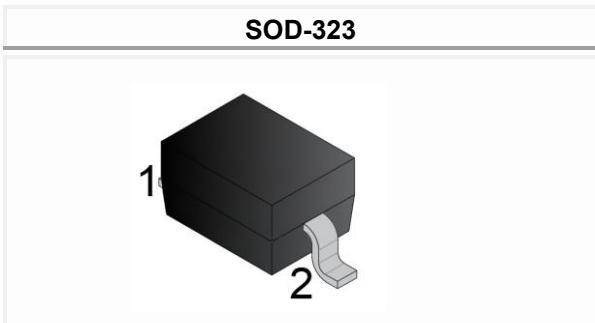
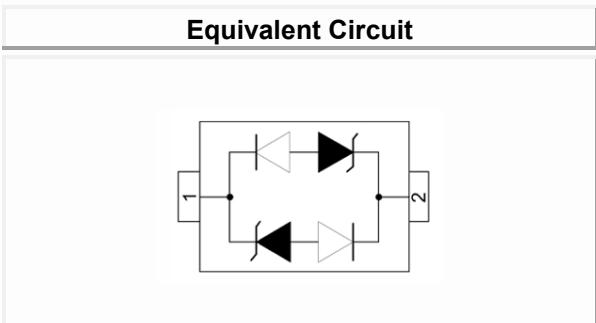
Features

- Operating Voltage: 3.3V
- IEC61000-4-2(ESD) $\pm 30\text{kV}$ (Air)
- IEC61000-4-2(ESD) $\pm 30\text{kV}$ (Contact)
- IEC61000-4-5 (Lightning) 21A (8/20 μs).

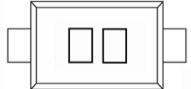
Mechanical Data

- SOD-323. Package
- RoHS Compliant and Halogen Free

Package and Pin Assignment

SOD-323	Equivalent Circuit
	

Ordering and Marking Information

GS P/N	Package	Marking	Quantity / Reel
GSE033HB1D3F	SOD-323	R3 or CC	3,000PCS
GSE033HB1D3F			
- Product Code: GSE033HB1	- Package Code: D3 for SOD-323	- Green Level: F for RoHS Compliant and Halogen Free	
Marking Information			
	- Product Code: □□ is R3 or CC		

Absolute Maximum Ratings (T_A=25°C unless otherwise specified)

Symbol	Parameter	Value	Unit
P _{PP}	Peak Pulse Power (t _P =8/20μs)	340	W
I _{PP}	Peak Pulse Current (t _P =8/20μs)	21	A
V _{ESD}	ESD Per IEC61000-4-2 (Air)	±30	kV
	ESD Per IEC61000-4-2 (Contact)	±30	kV
T _J	Operating Junction Temperature Range	-55 to +125	°C
T _{STG}	Storage Temperature Range	-55 to +150	°C

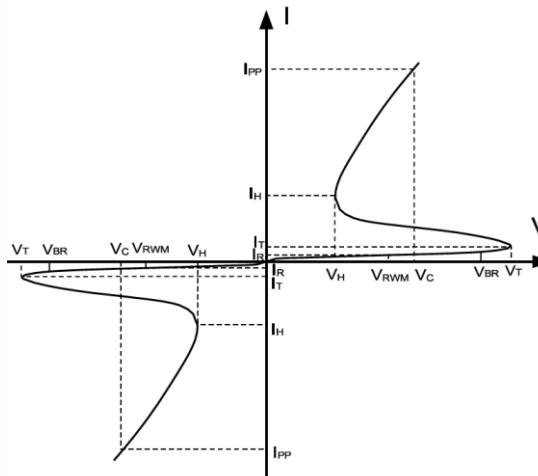
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Electrical Characteristics (T_A=25°C unless otherwise specified)

Symbol	Parameter	Conditions	Min	Typ	Max	Unit
V _{RWM}	Reverse Working Voltage	-			3.3	V
V _{BR}	Breakdown Voltage	I _T = 2µA	3.5			V
V _H	Holding Voltage	I _H = 50mA	2.8			V
I _R	Reverse Leakage Current	V _{RWM} =3.3V			0.2	µA
V _C	Clamping Voltage	I _{PP} =1A (8/20µs)			5	V
		I _{PP} =21A (8/20µs)			16	V
C _J	Junction Capacitance	V _R =0V, f=1MHz		1		pF

Electrical Parameters

Symbol	Parameter
I _{PP}	Reverse Peak Pulse Current
V _C	Clamping Voltage @ I _{PP}
V _{RWM}	Reverse Stand-Off Voltage
I _R	Reverse Leakage Current @ V _{RWM}
V _{BR}	Breakdown Voltage @ I _T
V _T	Test Voltage
I _T	Test Current
V _H	Holding Voltage
I _H	Holding Current



Typical Characteristics ($T_A=25^\circ\text{C}$ unless otherwise specified)

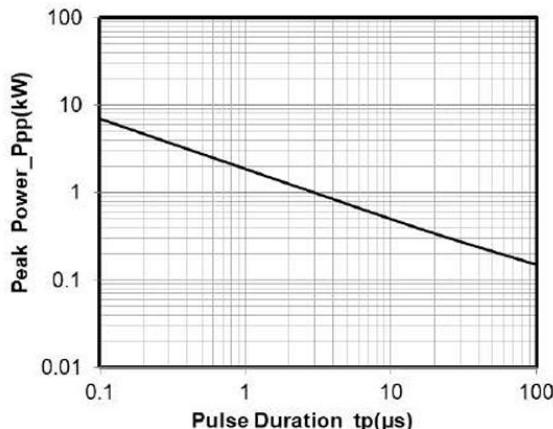


Fig 1. Peak Pulse Power vs. Pulse Time

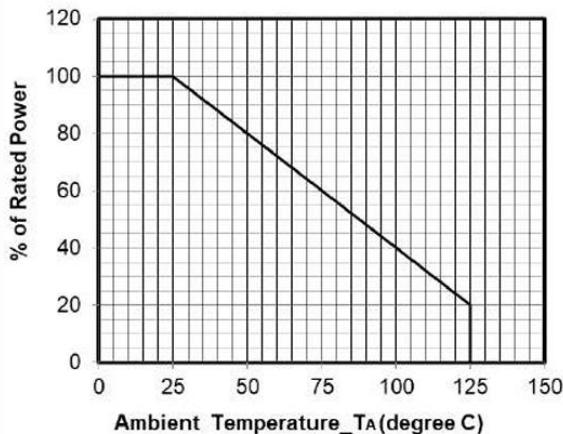


Fig 2. Power Derating Curve

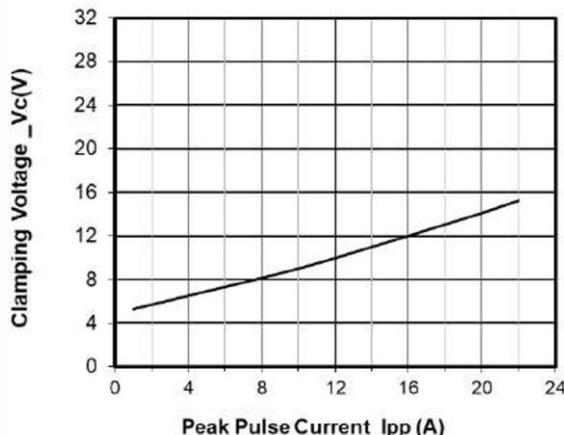


Fig 3. V_c vs. I_{pp} (8 X 20μs Pulse)

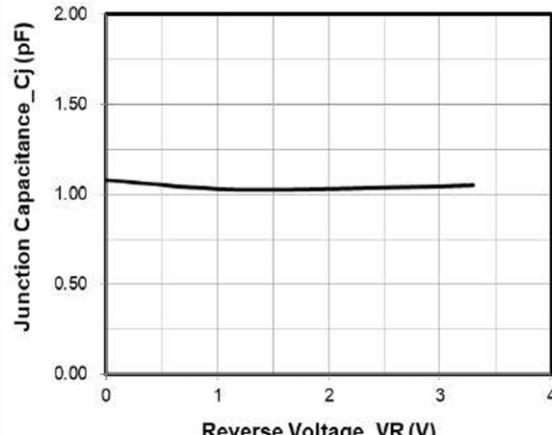


Fig 4. C_J vs. V_R

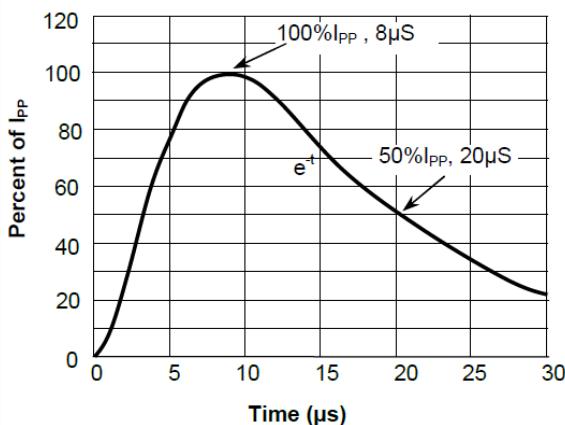
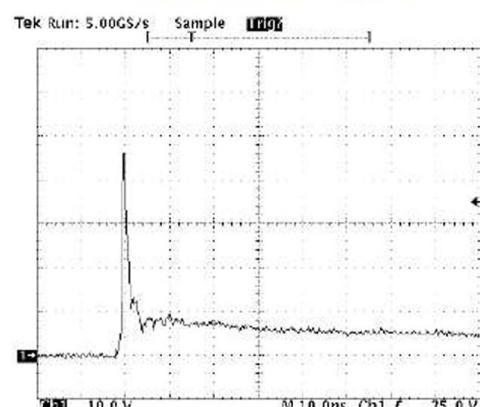


Fig 5. 8 X 20μs Pulse Waveform



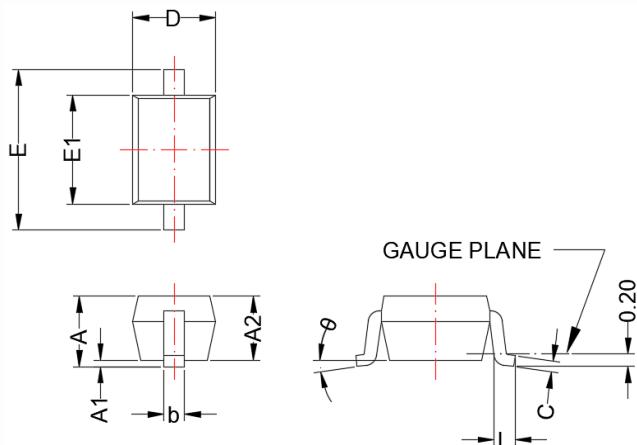
Note: Data is taken with a 10x attenuator

ESD Clamping Voltage

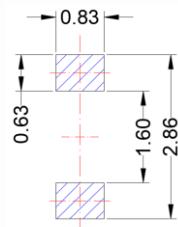
Fig 6. 8KV Contact per IEC61000-4-2

SOD-323

Package Dimension



Recommended Land Pattern



Unit:mm

Dimensions

Symbol	Millimeters		Inches	
	MIN	MAX	MIN	MAX
A	---	1.16	---	0.046
A1	0.00	0.14	0.000	0.006
A2	0.80	---	0.031	---
b	0.25	0.40	0.010	0.016
C	0.08	0.25	0.003	0.010
D	1.15	1.40	0.045	0.055
E	2.30	2.80	0.091	0.110
E1	1.40	1.80	0.055	0.071
L	0.08	---	0.003	---
θ	0°	8°	0°	8°

NOTE:

Dimensions are exclusive of Burrs, Mold Flash & Tie Bar extrusions.

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